TF Semiconductor Solutions

Features

- Drives two N-channel MOSFETs in a half bridge configuration
- Integrated bootstrap diode (BSD) included
- Floating high-side driver in bootstrap operation to 100V
- 1.5A source / 2.5A sink output current capability
- Undervoltage lockout for high and low side drivers
- Delay matching a maximum of 10ns
- Propagation delay a typical of 60ns
- Ultra low standby current (<1µA)</p>

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- Logic input (HIN, LIN, and EN) 3.3V capability
- Extended temperature range: -40°C to +125°C

TDFN-10

Space saving TDFN-10 3x3mm package

Applications

- BLDC Motor Drivers
- Battery Powered Hand Tools
- DC/DC converters



Description

The TF0579U is a high frequency gate driver capable of driving N-channel MOSFETs in a half bridge configuration. The floating high-side driver can switch to 100V in a bootstrap configuration.

The TF0579U contains an integrated bootstrap diode to greatly ease design and reduce the BOM.

The TF0579U logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with MCUs. UVLO for high side and low side will protect MOSFET with loss of supply. Also to protect MOSFETs, cross conduction prevention logic prevents the HO and LO to be on at the same time.

Fast and well matched propagation delays allow a higher switching frequency, enabling a smaller, more compact power switching design using smaller associated components. The TF0579U comes in a space-saving TDFN-10 package and operates over an extended -40 °C to +125 °C temperature range.

Ordering Information

Year Year Week Week

PART NUMBER	PACKAGE	PACK / Qty	MARK
TF0579U-NHS	TDFN-10	Tube / 120	YYWW
TF0579U-NHP	TDFN-10	T&R / 3,000	TF0579U

Typical Application



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100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD



Pin Descriptions

Top View

PIN NAME	PIN NUMBER	PIN DESCRIPTION
V _{cc}	1	Low-side and logic fixed supply
NC	2	No Connect
V _B	3	High-side floating supply
НО	4	High-side gate driver output
V _s	5	High-side floating supply return
EN	6	Logic input enable, a logic low turns off gate drivers
HIN	7	Logic input for high-side gate driver, in phase with HO
LIN	8	Logic input for low-side gate driver, in phase with LO
СОМ	9	Low-side and logic return
LO	10	Low-side gate drive output
СОМ	PAD	Low-side and logic return

Functional Block Diagram





100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD Absolute Maximum Ratings (NOTE1)

V - High side floating positive supply voltage	0.31/ to 1101/
$V_{\rm B}$ Thigh side floating positive supply voltage	$201/4 \times 10^{-10}$
v _s - High side floating negative supply voltagev _B	$-200 10 V_{B} + 0.50$
V _{HO} -Highside floating output voltageV _s	-0.3 V to V _B $+0.3$ V
dV _s /dt-Offset supply voltage transient	50 V/ns
V Logicondlow side Eved were hughtered	0.21/1 + 0.201/

v _{cc} -Logic and Low-side fixed supply voltage	0.3V to +20V
V ₁₀ - Low-side output voltage	0.3V to V_{cc} +0.3V
V _{IN} - Logic input voltage (HIN, LIN, and EN)	0.3V to V_{cc}^{c} +0.3V

NOTE1 Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

P_{D} - Package power dissipation at $T_{A} = 25 \text{ °C}$ TDFN-10	0.4W
TDFN-10 Thermal Resistance (NOTE2)	
θ _{JA}	64°C/W
$\theta_{\rm lc}$	42°C/W
T ₁ - Junction operating temperature	40°C to +150°C
T ₁ - Lead Temperature (soldering, 10 seconds)	+300°C
T _{sta} - Storage temperature	55°C to 150°C

NOTE2 When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Symbol	Parameter	MIN	МАХ	Unit
V _B	High side floating supply	V _s + 5.8	V _s + 18	V
V _s	High side floating supply offset voltage	NOTE3	100	V
V _{HO}	High side floating output voltage	Vs	V _B	V
V _{cc}	Logic and Low side fixed supply voltage	6.5	18	V
V _{LO}	Low side output voltage	0	V _{cc}	V
V _{IN}	Logic input voltage (HIN, LIN and EN)	0	5	V
T _A	Ambient temperature	-40	125	°C

NOTE3 Logic operational for VS of -5V to +100V.





100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD DC Electrical Characteristics (NOTE4)

 $V_{\rm CC}$ = $V_{\rm BS}$ = 12V, COM=V_{\rm S}=0V, $T_{\rm A}$ = 25 °C , unless otherwise specified.

Symbol	Parameter	Conditions	MIN	ТҮР	МАХ	Unit
V _{IH}	Logic "1" input voltage		2.4			
V _{IL}	Logic "0" input voltage	HIN and LIN, NOTES			0.8	v
V _{EIH}	Enable logic "1" input voltage		1.5			
V _{EIL}	Enable logic "0" input voltage	EN			0.5	
V _{INHYS}	Input voltage hysteresis			0.7		
V _{OH}	High level output voltage, V_{BIAS} - V_{O}	I ₀₊ = 10mA		0.05	0.3	
V _{OL}	Low level output voltage, V_{o}	I ₀₋ = 10mA		0.02	0.1	
I _{LK}	Offset supply leakage current	VB = VS = 100V		0.1	1	
I _{CCSD}	V _{cc} shutdown supply current	$V_{IN} = 0V \text{ or } 5V, V_{EN} = 0V$		0	1	μΑ
I _{ccq}	V _{cc} quiescent supply current	$V_{IN} = 0V \text{ or } 5V$		80	150	
I _{CCOP}	V _{cc} operating supply current	$fs = 500 \text{kHz}, C_L = 1 \text{nF}$		8.2		mA
I _{BSQ}	V _{BS} quiescent supply current	$V_{IN} = 0V \text{ or } 5V$		50	100	μA
I _{BSOP}	V _{BS} operating supply current	$fs = 500 \text{kHz}, C_L = 1 \text{nF}$		8.0		mA
I _{IN+}	Logic "1" input bias current	V _{IN} = 5V			50	
I _{IN-}	Logic "0" input bias current	V _{IN} =0V			5	μΑ
V _{BSUV+}	V _{BS} supply under-voltage positive going threshold		3.8	4.9	5.8	
V _{BSUV-}	V _{BS} supply under-voltage negative going threshold		3.3	4.5	5.3	V
V _{CCUV+}	V _{cc} supply under-voltage positive going threshold		4.0	5.2	6.0	
V _{CCUV-}	V _{cc} supply under-voltage negative going threshold		3.5	4.7	5.5	-
I _{O+}	Output high short circuit pulsed current	$V_{o} = 0V$, PW $\leq 10 \ \mu s$	1.0	1.5		
I _{o-}	Output low short circuit pulsed current	$V_{o} = 12V$, PW $\leq 10 \ \mu s$	1.5	2.5		A
V _{F1}	Forward voltage of boostrap diode	$I_F = 100 \mu A$		0.6	0.75	
V _{F2}	Forward voltage of boostrap diode	I _F =100mA		1.4	1.75	

NOTE4 The V_{IN} and I_{IN} parameters are applicable to the logic input pins: HIN, LIN, and EN. The V₀ and I₀ parameters are applicable to the respective output pins: HO and LO

NOTES For optimal operation, it is recommended that the input pulse (to HIN, LIN, and EN) should have an amplitude of 2.4V minimum with a pulse width of 140ns minimum.



100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD

AC Electrical Characteristics

 $V_{cc} = V_{BS} = 12V$, COM= V_{S} =0V, C_{L} = 1000pF, T_{A} = 25 °C , unless otherwise specified.

Symbol	Parameter	Conditions	MIN	ТҮР	МАХ	Unit
t _{on}	Turn-on propogation delay			65		
t _{off}	Turn-off propogation delay	V _s =100V		58		
t _{DM}	Delay matching, HS & LS turn-on			1	10	
t _r	Turn-on rise time			27		115
t _f	Turn-off fall time			20		





100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD





Figure 1. Switching Time Waveform Definitions

Figure 2. Delay Matching Waveform Definitions



Figure 3. Input / Output Timing Diagram





100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD

Typical Characteristics



















100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD

Package Dimensions (TDFN-10)

Please contact support@tfsemi.com for package availability.

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CVM (DOL	MILLIMETER			
STMBOL	MIN	NOM	MAX	
А	0.70	0.75	0.80	
A1	-	0.02	0.05	
ь	0.18	0.25	0.30	
с	D. 18	0.20	0.25	
D	2.90	3.00	3.10	
D_2	2.40	2.50	2.60	
с		0. 50BSC		
Nd		2.00BSC		
Е	2.90	3.00	3.10	
E2	1.45	1.55	1.65	
L	0.30	0.40	0.50	
h	0.20	0.25	0.30	



100V High Frequency High-Side and Low-Side Gate Driver with Integrated BSD

Revision History

Rev.	Change	Owner	Date
1.0	First release	Keith Spaulding	4/14/2020
1.1	Add Enable logic input threshold specification	Keith Spaulding	6/10/2020
1.2	Electrical specs changed to match early production data, and some graphs added.	Keith Spaulding	8/1/2020

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